Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2733

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 8.0 Ω (typ.)

• High forward transfer admittance : $|Y_{fs}| = 0.9 \text{ S (typ.)}$ • Low leakage current : $IDSS = 100 \mu A \text{ (max) (VDS} = 720 \text{ V)}$

• Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	1	Α	
	Pulse (Note 1)	I_{DP}	3	"	
Drain power dissipation	n (Tc = 25°C)	P_{D}	60	W	
Single pulse avalanche energy (Note 2)		E _{AS}	324	mJ	
Avalanche current		I _{AR}	1	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	6.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

Weight: 2.0 (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.08	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 594 mH, R_{G} = 25 Ω , I_{AR} = 1 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

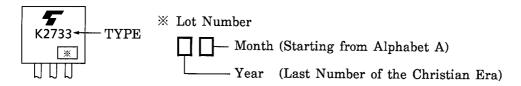
Electrical Characteristics (Ta = 25°C)

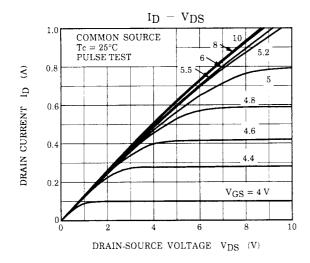
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V _(BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 0.5 A	_	8.0	9.0	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 0.5 A	0.2	0.9	_	S
Input capacitanc	е	C _{iss}			370	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	5	_	
Output capacitance		C _{oss}			40	_	1
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{_{0V}} \stackrel{I_{D}=1A}{_{CI}} \circ V_{out}$ $R_{L}=200\Omega$ $V_{DD}=200V$	_	20	_	- ns
	Turn-on time	t _{on}		_	70	_	
	Fall time	t _f		_	30	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_w = 10 \mu s$	_	95	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	15	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}$		6	_	nC
Gate-drain ("miller") Charge		Q_{gd}			9	_	

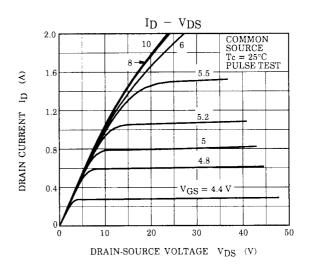
Source-Drain Ratings and Characteristics (Ta = 25°C)

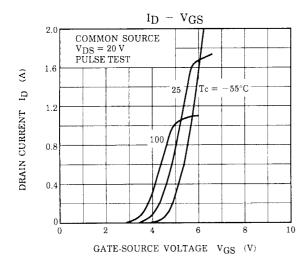
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	1	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	3	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 1 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 1 A, V _{GS} = 0 V		750	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	3	_	μC

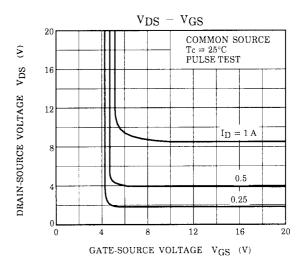
Marking

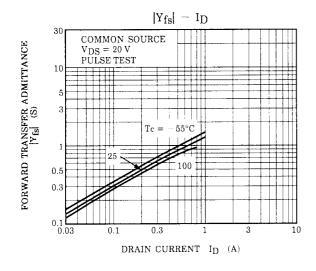


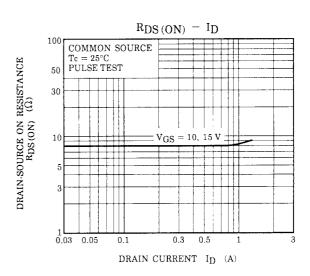




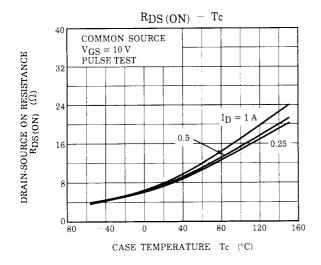


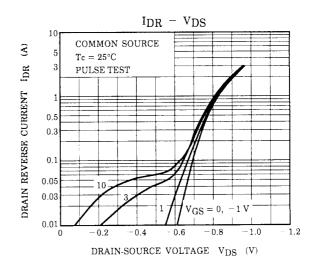


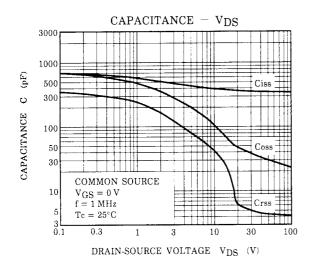


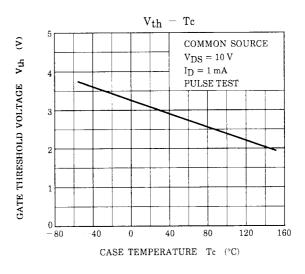


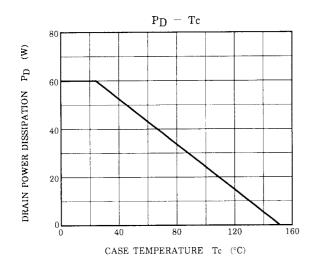
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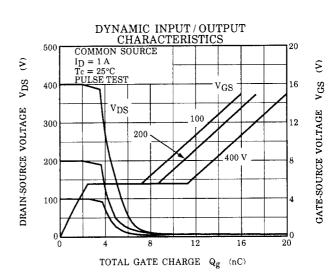




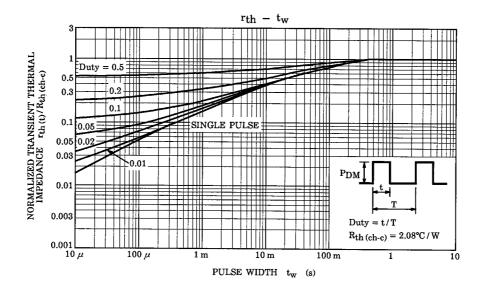


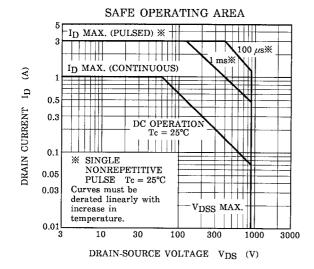


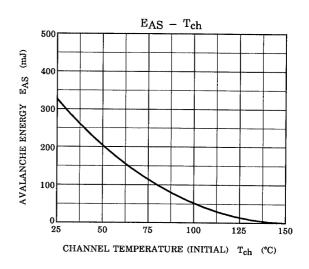


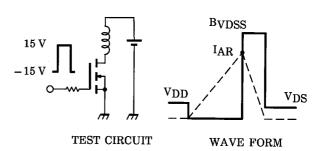


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 594~mH \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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